Vishay Siliconix

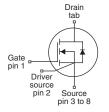
HALOGEN

FREE

E Series Power MOSFET

PowerPAK® 10 x 12





N-Channel	MOSFET

PRODUCT SUMMARY					
V _{DS} (V) at T _J max.	65	50			
R _{DS(on)} typ. (Ω) at 25 °C	V _{GS} = 10 V	0.059			
Q _g max. (nC)	7	2			
Q _{gs} (nC)	1	9			
Q _{gd} (nC)	11				
Configuration	Sin	gle			

FEATURES

- 4th generation E series technology
- Low figure-of-merit (FOM) Ron x Qg
- Low effective capacitance (Co(er))
- Reduced switching and conduction losses
- Avalanche energy rated (UIS)
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- · Server and telecom power supplies
- Switch mode power supplies (SMPS)
- Power factor correction power supplies (PFC)
- Lighting
 - High-intensity discharge (HID)
 - Fluorescent ballast lighting
- Industrial
 - Welding
 - Induction heating
 - Motor drives
 - Battery chargers
 - Solar (PV inverters)

ORDERING INFORMATION	
Package	PowerPAK 10 x 12
Lead (Pb)-free and halogen-free	SiHK065N60E-T1-GE3

ABSOLUTE MAXIMUM RATINGS (T _C = 25 °C, unless otherwise noted)						
PARAMETER			SYMBOL	LIMIT	UNIT	
Drain-source voltage			V _{DS}	600	V	
Gate-source voltage			V_{GS}	± 30		
Continuous drain current (T _J = 150 °C)	V _{GS} at 10 V	$T_{\rm C} = 25 ^{\circ}{\rm C}$ $T_{\rm C} = 100 ^{\circ}{\rm C}$	- I _D	34	A	
	VGS at 10 V	T _C = 100 °C		21		
Pulsed drain current ^a			I _{DM}	98	1	
Linear derating factor				1.54	W/°C	
Single pulse avalanche energy b			E _{AS}	226	mJ	
Maximum power dissipation			P _D 192		W	
Operating junction and storage temperature range			T _J , T _{stg}	-55 to +150	°C	
Drain-source voltage slope		T _J = 125 °C	dv/dt	100	V/ns	
Reverse diode dv/dt ^d			uv/dt	21	V/IIS	

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature
- b. V_{DD} = 120 V, starting T_J = 25 °C, L = 28.2 mH, R_g = 25 Ω , I_{AS} = 4.0 A
- c. 1.6 mm from case
- d. $I_{SD} \le I_D$, di/dt = 100 A/ μ s, starting T_J = 25 °C



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THERMAL RESISTANCE RATINGS					
PARAMETER	SYMBOL	TYP.	MAX.	UNIT	
Maximum junction-to-ambient	R _{thJA}	=	50 ^c	°C/W	
Maximum junction-to-case (drain)	R_{thJC}	-	0.65	C/VV	

PARAMETER	SYMBOL	TES	TEST CONDITIONS		TYP.	MAX.	UNIT
Static							
Drain-source breakdown voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		600	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	Reference to 25 °C, I _D = 1 mA		-	0.69	-	V/°C
Gate-source threshold voltage (N)	V _{GS(th)}	V _{DS} =	$V_{DS} = V_{GS}, I_D = 250 \mu\text{A}$		-	5.0	V
Cata acuraa laakaga	1	V _{GS} = ± 20 V		-	-	± 100	nA
Gate-source leakage	I_{GSS}	V _{GS} = ± 30 V		-	-	± 1	μΑ
Zero gate voltage drain current		V _{DS} =	600 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	$V_{DS} = 480 \text{ V}$	$^{\circ}$, $V_{GS} = 0 \text{ V}$, $T_{J} = 125 ^{\circ}\text{C}$	-	-	10	μA
Drain-source on-state resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 15 A	-	0.059	0.068	Ω
Forward transconductance ^a	9 _{fs}	V _{DS}	= 10 V, I _D = 15 A	-	3.6	-	S
Dynamic							
Input capacitance	C_{iss}	V _{GS} = 0 V,		-	2946	-	pF
Output capacitance	C _{oss}	,	$V_{DS} = 100 \text{ V},$		124	-	
Reverse transfer capacitance	C_{rss}	f = 1 MHz		-	5	-	
Effective output capacitance, energy related ^a	$C_{o(er)}$	V _{DS} = 0 V to 480 V, V _{GS} = 0 V		-	88	-	
Effective output capacitance, time related ^b	$C_{o(tr)}$			-	554	-	
Total gate charge	Qg			-	48	72	
Gate-source charge	Q_{gs}	$V_{GS} = 10 \text{ V}$ $I_D = 15 \text{ A}, V_{DS} = 480 \text{ V}$		-	19	-	nC
Gate-drain charge	Q_{gd}				11	-	
Turn-on delay time	t _{d(on)}	V _{DD} = 480 V, I _D = 15 A,		-	28	56	
Rise time	t _r			-	33	66	no
Turn-off delay time	t _{d(off)}	V _{GS} =	$V_{GS} = 10 \text{ V}, R_g = 9.1 \Omega$		51	77	ns
Fall time	t _f	1		-	9	18	
Gate input resistance	R_g	f = 1 MHz		0.4	0.8	1.6	Ω
Drain-Source Body Diode Characteristic	s						
Continuous source-drain diode current	Is	MOSFET symbol showing the integral reverse p - n junction diode		-	-	34	
Pulsed diode forward current	I _{SM}			-	-	98	A
Diode forward voltage	V _{SD}	T _J = 25 °C, I _S = 15 A, V _{GS} = 0 V		-	-	1.2	V
Reverse recovery time	t _{rr}	$T_J = 25 \text{ °C}, I_F = I_S = 15 \text{ A},$ $di/dt = 100 \text{ A/}\mu\text{s}, V_R = 25 \text{ V}$		-	346	692	ns
Reverse recovery charge	Q _{rr}			-	4.7	9.4	μC
Reverse recovery current	I _{RRM}			_	23	-	A

Notes

- a. $C_{oss(er)}$ is a fixed capacitance that gives the same energy as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- b. $C_{oss(tr)}$ is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 % to 80 % V_{DSS}
- c. When mounted on 1" x 1" FR4 board



TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

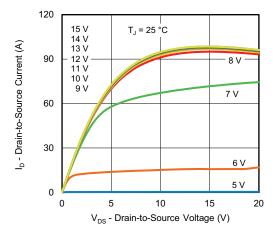


Fig. 1 - Typical Output Characteristics

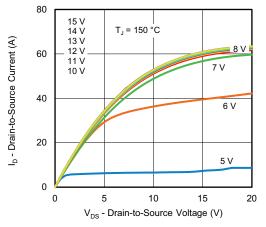


Fig. 2 - Typical Output Characteristics

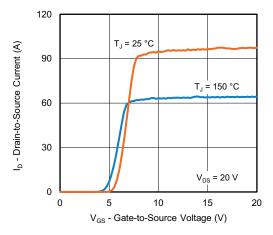


Fig. 3 - Typical Transfer Characteristics

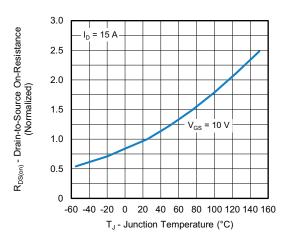


Fig. 4 - Normalized On-Resistance vs. Temperature

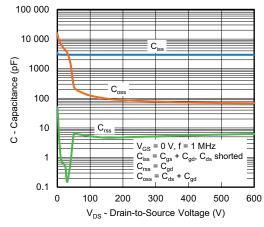


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

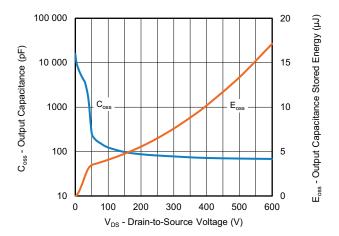


Fig. 6 - C_{oss} and E_{oss} vs. V_{DS}



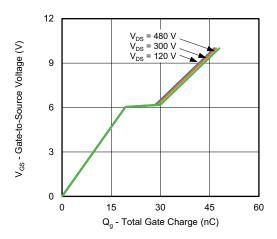


Fig. 7 - Typical Gate Charge vs. Gate-to-Source Voltage

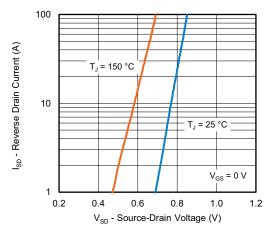


Fig. 8 - Typical Source-Drain Diode Forward Voltage

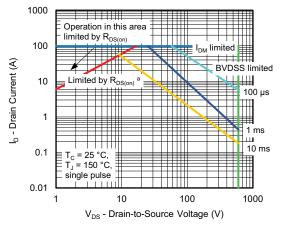


Fig. 9 - Maximum Safe Operating Area



a. V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

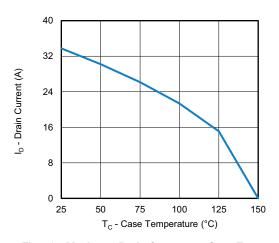


Fig. 10 - Maximum Drain Current vs. Case Temperature

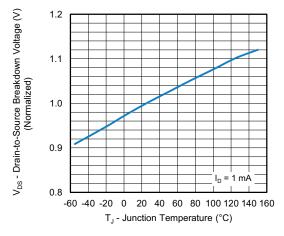


Fig. 11 - Temperature vs. Drain-to-Source Voltage



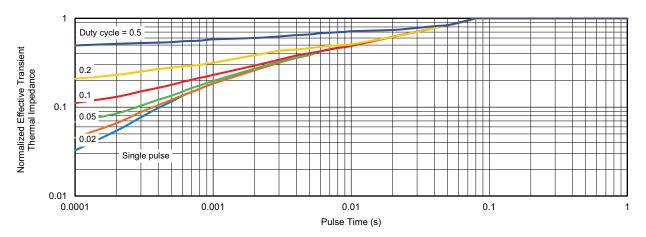


Fig. 12 - Normalized Transient Thermal Impedance, Junction-to-Case

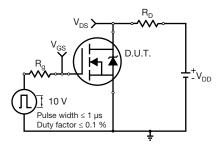


Fig. 13 - Switching Time Test Circuit

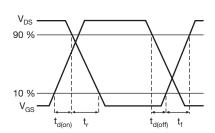


Fig. 14 - Switching Time Waveforms

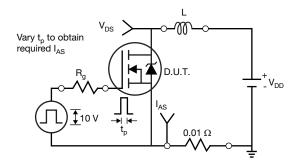


Fig. 15 - Unclamped Inductive Test Circuit

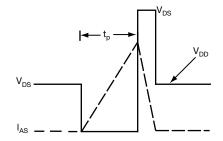


Fig. 16 - Unclamped Inductive Waveforms

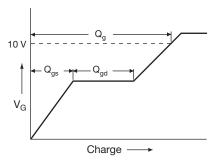


Fig. 17 - Basic Gate Charge Waveform

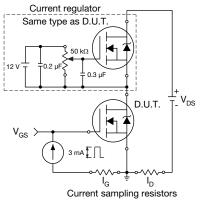
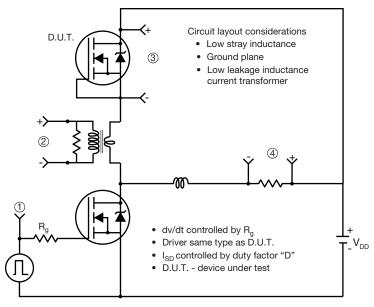


Fig. 18 - Gate Charge Test Circuit



Peak Diode Recovery dv/dt Test Circuit



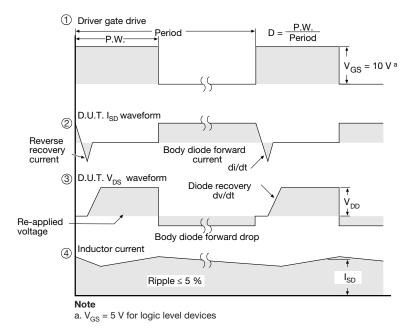
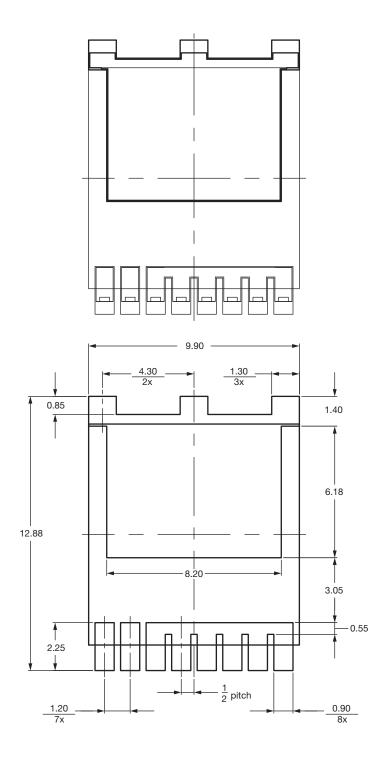


Fig. 19 - For N-Channel

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Recommended Land Pattern PowerPAK® 10 x 12 (TOLL) (High Voltage)



Note

• Dimensions in mm

ECN: S22-1061-Rev. C, 26-Dec-2022

DWG: 3013



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